



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

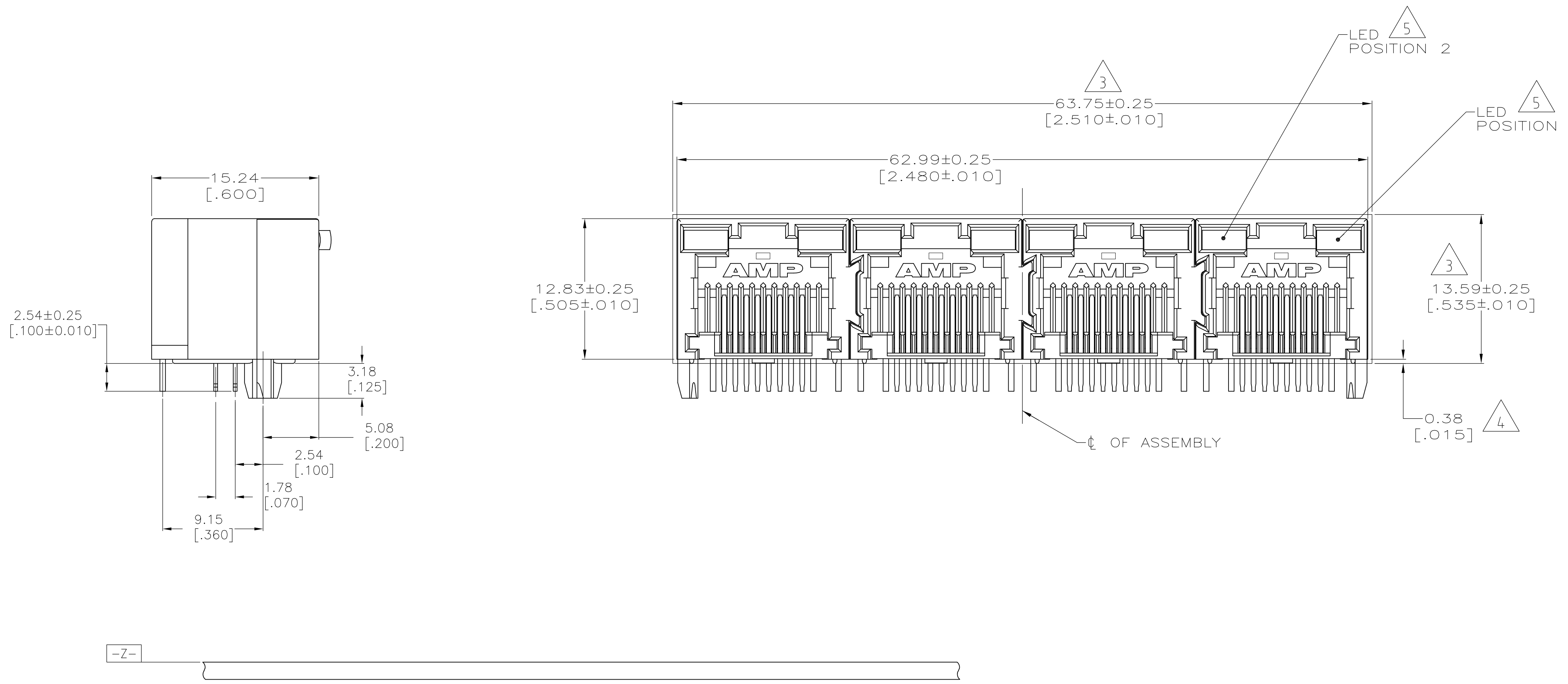
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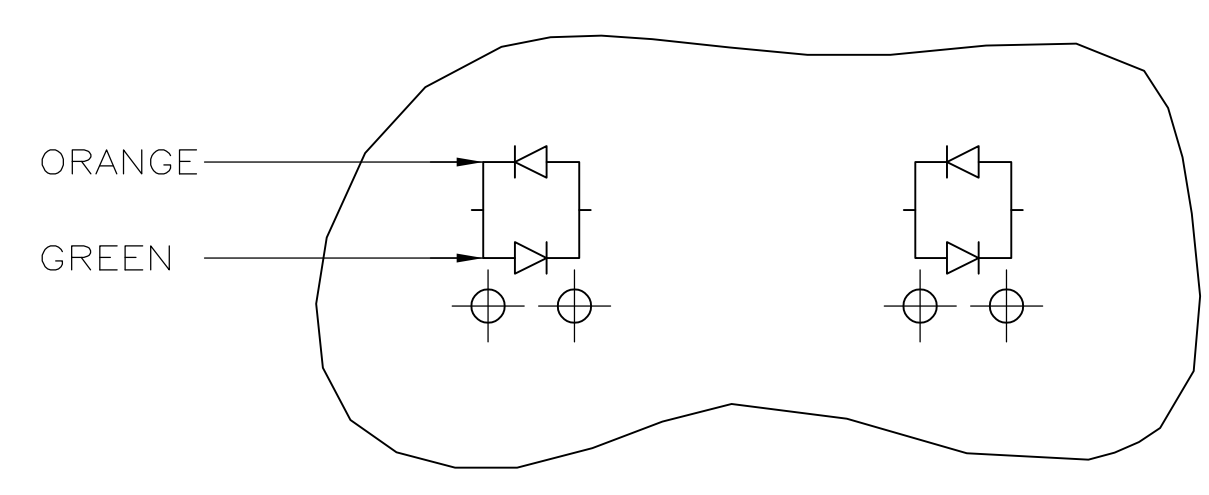
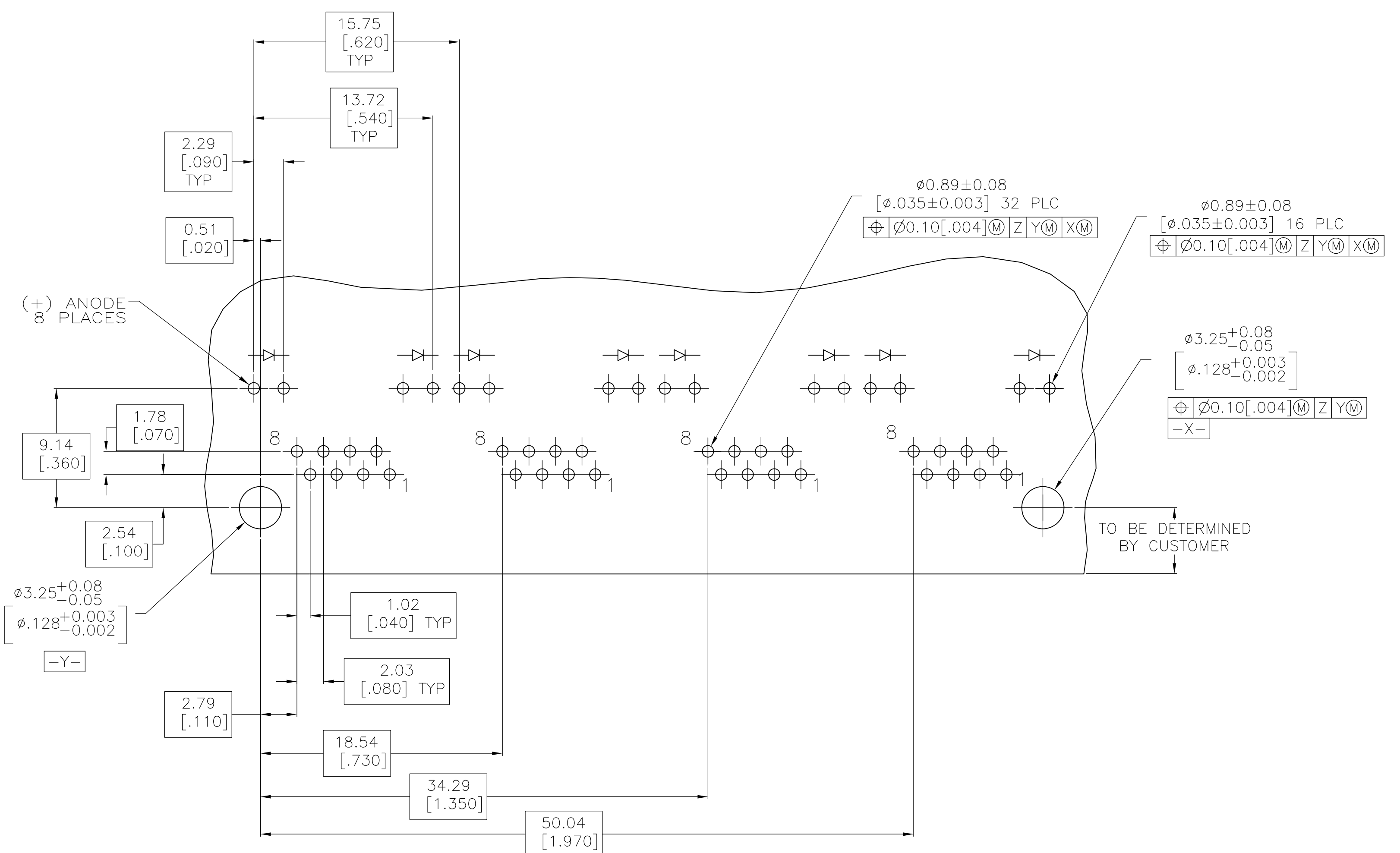
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



LOC		DIST		REVISIONS			
AA	00	REV	DESCRIPTION	DATE	BY	APPV	
C		ECO-07-022131		03NOV07	LAM	JW	
C1		REVISED PER ECO-09-021510		12SEP09	KK	AEG	



- MATERIAL:  
 HOUSING - HIGH TEMPERATURE THERMOPLASTIC, BLACK, UL94V-0.  
 TERMINALS - .36[.014] THICK PHOS BRONZE PLATED WITH 3.81µm[.000150] MIN THICK BRIGHT TIN LEAD IN SOLDER AREA. 1.27µm [.000050] MINIMUM GOLD IN LOCALIZED PLATE AREA. ENTIRE TERMINAL PLATED WITH 1.27µm [.000050] MINIMUM THICK NICKEL.  
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, .51 x .51[.020 x .020] CARBON STEEL WIREFRAME LEADS PLATED WITH 8.89µm[.000350] TIN/COPPER OVER 2.03µm[.000080] SILVER OVER 1.02µm[.000040] NICKEL UNDERPLATE OVER 2.03µm[.000080] COPPER UNDERPLATE.
  - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
- △ SUGGESTED PANEL OPENING DIMENSIONS.  
 △ SUGGESTED CLEARANCE BETWEEN BOTTOM OF CONNECTOR AND BOTTOM PANEL OPENING.  
 △ SEE TABLE FOR COLOR OF LEDS AND NUMBER REQUIRED.  
 6. THIS MODULAR JACK WITH INTEGRATED LED IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.  
 △ OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI



LED CURRENT DIAGRAM  
 406536-7 ONLY

	ORANGE/GREEN	ORANGE/GREEN	406536-7
△ OBSOLETE	YELLOW	YELLOW	406536-6
△ OBSOLETE	GREEN	GREEN	406536-5
△ OBSOLETE	GREEN	YELLOW	406536-4
△ OBSOLETE	YELLOW		406536-3
△ OBSOLETE		GREEN	406536-2
	YELLOW	GREEN	406536-1
	POSITION 2	POSITION 1	
	INDICATOR COLOR FOR EACH HOUSING		PART NUMBER

RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT  
 (COMPONENT SIDE)

THIS DRAWING IS A CONTROLLED DOCUMENT.

DIMENSIONS: mm [INCHES]	TOLERANCES UNLESS OTHERWISE SPECIFIED:	DIN T. SPRINKLE 20SEP97	CHK T. SPRINKLE 20SEP97	APVD M. DERSTINE 20SEP97	NAME	Tyco Electronics Corporation Harrisburg, PA 17105-3608
0 PLC ± -	1 PLC ± -	2 PLC ± 0.25[.01]	3 PLC ± 0.13[.005]	4 PLC ± -	ANGLES ± -	PRODUCT SPEC
108-1163-4	114-2154	SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO	
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	WEIGHT	A1	00779	406536	
CUSTOMER DRAWING		SCALE	4:1	SHEET	1 of 1	REV